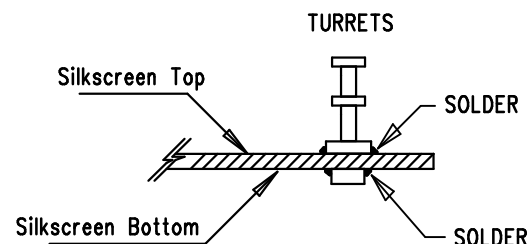


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	1ST PROTOTYPE	CLARENCE M.	10-22-10
	N/A	-G ASS'Y OPT ADDED	CLARENCE M.	03-05-13

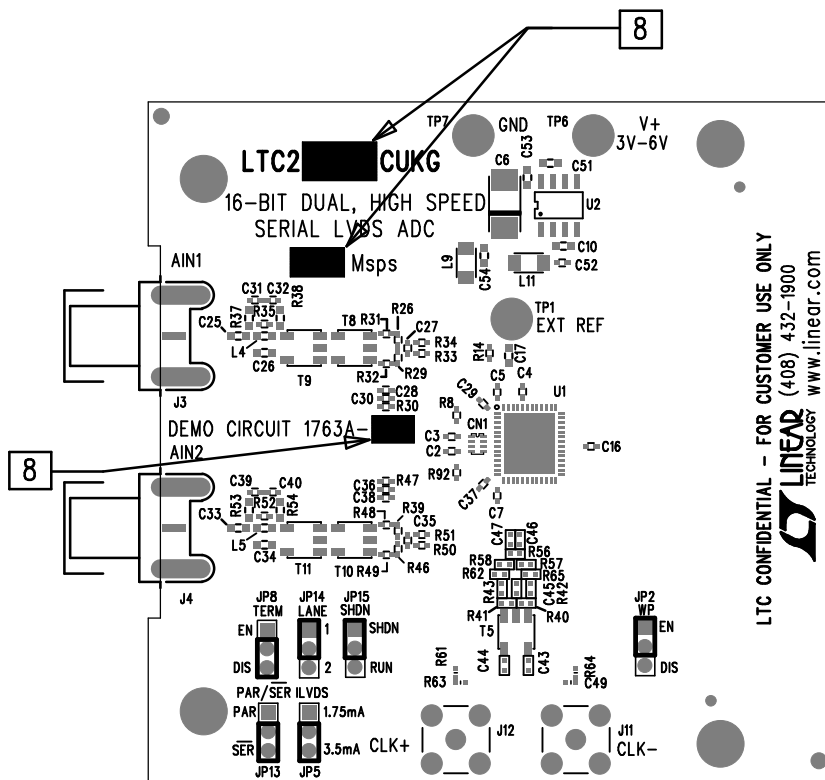
NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEG. CELCIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL TURRETS, QTY 3, FOR TP1, TP6 AND TP7. AS SHOWN:



8. MARK EACH LTC PART NUMBER AND ASSEMBLY TYPE WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1	MspS
-A	LTC2195CUKG	125
-B	LTC2194CUKG	105
-C	LTC2193CUKG	80
-D	LTC2192CUKG	65
-E	LTC2191CUKG	40
-F	LTC2190CUKG	25
-G	LTC2271CUKG	20



APPROVALS

PCB DES.	MH
APP ENG.	CLARENCE M.
SCALE = NONE	



TITLE: TOP ASSEMBLY DRAWING 16-BIT DUAL, HIGH SPEED, SERIAL LVDS ADC		
SIZE N/A	IC NO. LTC2195CUKG DEMO CIRCUIT 1763A	REV. 1
FILENAME: DC1763A-1.PCB		SHT 1 OF 2